

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A method of fabricating a semiconductor device comprising, in order, the steps of:
 - (a) attaching a plurality of semiconductor chips to a continuous semiconductor substrate tape in a reel-to-reel transport system;
 - (b) cutting the continuous semiconductor substrate tape to obtain individual semiconductor substrates, each including a single semiconductor chip after the step (a); and
 - (c) providing a plurality of external terminals on each of the individual semiconductor substrates ~~after the step (b);~~

~~wherein the steps (a) and (b) are carried out in a reel-to-reel transport system.~~
2. (Currently Amended) The method of fabricating a semiconductor device as defined in claim 1, step (a) further comprising:

attaching a reinforcing member to the continuous semiconductor substrate tape ~~in at~~ positions corresponding to each of the semiconductor chips, ~~before the step (b).~~
3. (Currently Amended) The method of fabricating a semiconductor device as defined in ~~claim 1~~claim 9,

wherein step (d) includes cutting the continuous semiconductor substrate tape ~~is cut~~ into regions each including one of the semiconductor chips ~~in the step (b).~~
4. (Canceled)
5. (Currently Amended) The method of fabricating a semiconductor device as defined in ~~claim 1~~claim 9,

wherein step (d) includes cutting the continuous semiconductor substrate tape ~~is cut~~ into regions each including two or more of the semiconductor chips ~~in the step (b).~~

6. (Canceled)

7. (Currently Amended) The method of fabricating a semiconductor device as defined in claim 5, further comprising:

cutting each of the ~~substrates into regions~~ into subregions, each including one of the semiconductor chips, after the ~~step (e)~~ step (e).

8. (Canceled)

9. (Currently Amended) ~~The A~~ method of fabricating a semiconductor device comprising, in order, the steps of:

(a) providing a continuous semiconductor substrate tape in a reel-to-reel transport system, including forming~~wherein~~ a plurality of device holes are formed in the continuous semiconductor substrate tape and forming leads ~~are formed on the continuous semiconductor substrate tape, which~~ where end portions of the leads project into the respective device holes; ~~and~~

(b) attaching a reinforcing member to the continuous semiconductor substrate tape at positions corresponding to the respective device holes;

(c) attaching a plurality of semiconductor chips to the continuous semiconductor tape, including disposing~~wherein~~ each of the semiconductor chips is ~~disposed~~ within a respective one of the device holes, and bonding the leads with electrodes of the semiconductor chips ~~and the leads are bonded in the step (a);~~

(d) cutting the continuous semiconductor substrate tape to obtain individual semiconductor substrates; and

(e) providing a plurality of external terminals on each of the individual semiconductor substrates.

10. (Withdrawn) The method of fabricating a semiconductor device as defined in claim 1,

wherein each of the semiconductor chips is bonded to the tape in a face-down configuration in the step (a).

11. (Withdrawn) The method of fabricating a semiconductor device as defined in claims 10,

wherein by means of an anisotropic conductive material, the electrodes of the semiconductor chips and leads formed above the tape are electrically connected in the step (a).

12. (Currently Amended) The method of fabricating a semiconductor device as defined in claim 1,

wherein step (a) further includes bonding each of the semiconductor chips is ~~bonded to the~~ continuous semiconductor substrate tape in a face-up configuration ~~in the step~~ (a).

13. (Currently Amended) The method of fabricating a semiconductor device as defined in claim 12,

wherein step (a) further includes electrically connecting with wires ~~the~~ electrodes of the semiconductor chips and leads formed on the continuous semiconductor substrate ~~tape are electrically connected by means of wires in the step (a).~~

14. (Previously Presented) The method of fabricating a semiconductor device as defined in claim 1, further comprising:

attaching a heat radiating member to each of the semiconductor chips.

15. (Previously Presented) The method of fabricating a semiconductor device as defined in claim 2, further comprising:

attaching a heat radiating member to each of the semiconductor chips.

16. (Currently Amended) The method of fabricating a semiconductor device as defined in claim 1, step (a) further comprising:

attaching ~~the~~ a heat radiating member ~~before the step (b), with a reel-to-reel transport system.~~

17. (Currently Amended) The method of fabricating a semiconductor device as defined in claim 2, step (a) further comprising:

attaching ~~the~~ a heat radiating member ~~before the step (b), with a reel-to-reel transport system.~~

18. (Original) A semiconductor device fabricated by the method as defined in claim 1.

19. (Original) A circuit board having mounted the semiconductor device as defined in claim 18.

20. (Original) An electronic apparatus including the semiconductor device as defined in claim 18.

21. (New) The method of fabricating a semiconductor device as defined in claim 9, step (a) further comprising:

attaching a heat radiating member to each of the semiconductor chips.

22. (New) A semiconductor device fabricated by the method as defined in claim 9.

23. (New) An electronic apparatus including the semiconductor device as defined in claim 22.